## Large Current External FET Controller Type Switching Regulators

## Single-output Step-up, Negative Voltage,

 Step-down Switching Regulators (Controller type)
## BD9300F/BD9300FV

## - Description

The BD9300F/FV 1-channel DC/DC Step-up, step-down, and inverting converter controller.
This IC has a wide input voltage range of 3.6 to 35 V , providing for a variety of applications. The pin assignment is similar to that of the BA9700, facilitating a space-saving application.

## Features

1) 1-channel PWM control DC/DC converter controller
2) High voltage input of 3.6 to 35 V
3) Reference voltage accuracy of $\pm 1 \%$
4) Oscillation frequency variable in the range of 20 to 800 kHz
5) Built-in UVLO (Under Voltage Lock Out) circuit and SCP (Short Circuit Prevention) circuit
6) Current in standby mode: $0 \mu \mathrm{~A}$ (typ.)
7) Switching external synchronization available (Slave operation)
8) SSOP-B14 Package (for BD9300FV) or SOP14 Package (for BD9300F)

Applications

- TV, power supply for liquid crystal display TV, and backlight
- DSC, DVD, printer, DVD/DVD recorder, and other consumer products

- Absolute maximum ratings $\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)$

| Item | Symbol | Rating | Unit |
| :--- | :---: | :---: | :---: |
| Power supply voltage | Vcc | 36 | V |
| Power dissipation | Pd | 400 | ${ }^{*}$ |
| Operating temperature | Topr | -40 to +85 | $\mathrm{~mW}^{\circ} \mathrm{C}$ |
| Storage temperature | Tstg | -55 to +125 | ${ }^{\circ} \mathrm{C}$ |
| Output current | Io | 100 | ${ }^{* *}$ |
| Output voltage | Vo | 36 | mA |
| Maximum junction temperature | Tjmax | 125 | V |

* Reduce by $4 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ over $25^{\circ} \mathrm{C}$, when mounted on a glass epoxy PCB of 70 mmX 70 mmX 1.6 mm )
* Should not exceed Pd-value.
- Recommended operating range $\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)$

| Item | Symbol | Limits |  |  | Unit |
| :--- | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Typ | Max |  |
| Power supply voltage | Vcc | 3.6 | 12 | 35 | V |
| Output sink current | Io | - | - | 30 | mA |
| Output voltage | Vo | - | - | 35 | V |
| Timing capacitance | CT | 33 | - | 1000 | pF |
| Timing resistance | RT | 5 | - | 100 | $\mathrm{k} \Omega$ |
| Oscillation frequency | Fosc | 20 | - | 800 | kHz |

- Electrical characteristics (Unless otherwise specified, $\mathrm{Ta}=25^{\circ} \mathrm{C}, \mathrm{Vcc}=12 \mathrm{~V}, \mathrm{CT}=200 \mathrm{pF}, \mathrm{RT}=20 \mathrm{k} \Omega$ )

| Item | Symbol | Limits |  |  | Unit | Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Typ | Max |  |  |
| [Reference voltage block] |  |  |  |  |  |  |
| Reference voltage | Vref | 2.475 | 2.500 | 2.525 | V | I REF $=1 \mathrm{~mA}$ |
| Input stability | VDLI | - | 1.5 | 20 | mV | $\begin{aligned} & \text { Vcc=3.6 to } 35 \mathrm{~V} \\ & \text { IREF=1mA } \end{aligned}$ |
| Load stability | Vdld | - | 0.5 | 20 | mV | IREF $=0 \sim 1 \mathrm{~mA}$ |
| 1/2 reference voltage | 1/2VREF | 1.212 | 1.25 | 1.288 | V |  |
| [Triangular wave oscillator block] |  |  |  |  |  |  |
| Oscillation frequency | Fosc | 165 | 220 | 275 | kHz |  |
| Charge mode threshold voltage | Vosc ${ }^{+}$ | - | 1.95 | - | V |  |
| Discharge mode threshold voltage | Vosc- | - | 1.45 | - | V |  |
| Frequency variation | Fovo | - | 1 | - | \% | $\mathrm{Vcc}=3.6$ to 35 V |
| [Protection circuit block] |  |  |  |  |  |  |
| Threshold voltage | VIT | 1.5 | 1.8 | 2.1 | V |  |
| Charge current | Iscp | - | 7 | 11 | $\mu \mathrm{A}$ |  |
| [Rest period adjustment circuit block] |  |  |  |  |  |  |
| Upper limit threshold voltage | Vth | 2.05 | - | - | V | Duty Cycle=0\% |
| Lower limit threshold voltage | VtL | - | - | 1.35 | V | Duty Cycle=100\% |
| Input bias current | lbd | - | 0.1 | 1 | $\mu \mathrm{A}$ | DTC=1.5V |
| Latch mode charge current | Idtc | 200 | 500 | - | $\mu \mathrm{A}$ | DTC=0V |
| [Under voltage lock out block] |  |  |  |  |  |  |
| Threshold voltage | Vut | - | 2.8 | - | V |  |

O Not designed to be radiation-resistant.

- Electrical characteristics (Unless otherwise specified, $\mathrm{Ta}=25^{\circ} \mathrm{C}, \mathrm{Vcc}=12 \mathrm{~V}, \mathrm{CT}=200 \mathrm{pF}, \mathrm{RT}=20 \mathrm{k} \Omega$ )

| Item | Symbol | Limits |  |  | Unit | Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Typ | Max |  |  |
| [Error amplifier block] |  |  |  |  |  |  |
| Input bias current | 118 | - | 0.1 | 1 | $\mu \mathrm{A}$ |  |
| Open loop gain | AV | - | 85 | - | dB | Null AMP |
| Maximum output voltage | Vor | 2.3 | 2.5 | - | V |  |
| Minimum output voltage | Vol | - | 0.7 | 0.9 | V |  |
| Output sink current | IoI | 0.1 | 1 | - | mA | $V_{F B}=1.25 \mathrm{~V}$ |
| Output source current | Ioo | 40 | 70 | - | $\mu \mathrm{A}$ | $V_{F B}=1.25 \mathrm{~V}$ |
| [Output block] |  |  |  |  |  |  |
| Saturation voltage | Vsat | - | 1.0 | 1.4 | V | $1 \mathrm{c}=30 \mathrm{~mA}$ |
| Leak current | ILEAK | - | - | 10 | $\mu \mathrm{A}$ | OUT $=35 \mathrm{~V}$ |
| [Control block] |  |  |  |  |  |  |
| CTL ON voltage | Von | 2 | - | - | V |  |
| CTL OFF voltage | Voff | - | - | 0.7 | V |  |
| CTL sink current | IctL | - | 57 | 90 | $\mu \mathrm{A}$ | Vстц=5V |
| [Whole device] |  |  |  |  |  |  |
| Standby current | Istb | - | 0 | 10 | $\mu \mathrm{A}$ | Vctl=0V |
| Average supply current | Icc | - | 1.2 | 2.4 | mA | $\mathrm{RT}=\mathrm{VREF}$ |

Not designed to be radiation-resistant.

## - Measurement circuit diagram



Fig. 1 Typical measurement circuit


Fig. 2 Reference voltage vs. Ambient temperature


Fig. 5 Circuit current


Fig. 8 Control threshold voltage


Fig. 3 Switching frequency vs. Ambient temperature


Fig. 6 Reference voltage


Fig. 9 Output current capacitance


Fig. 4 Standby current


Fig. 7 Reference voltage vs. Output current


Fig. 10 Control sink current


Fig. 11 Pin assignment / Block diagram

- Pin assignment and function

| Pin No. | Pin name | Function |
| :---: | :---: | :--- |
| 1 | DTC | Rest period setting voltage input |
| 2 | RT | External timing resistance |
| 3 | CT | External timing capacitance |
| 4 | FB | Error amplifier output |
| 5 | OUT | PWM output (open collector) |
| 6 | N.C. | - |
| 7 | GND | Ground |
| 8 | Vcc | Power supply |
| 9 | SCP | External timer latch setting capacitance (Ground if not used) |
| 10 | CTL | Control input |
| 11 | VREF | Reference voltage output |
| 12 | INV | Inverting input for error amplifier |
| 13 | $1 / 2$ VREF | $1 / 2$ reference voltage output |
| 14 | NON | Non-inverting input for error amplifier |
| 14 |  |  |



Fig. 12 Typical application circuit

## VREF block

The VREF block is a block to output a reference voltage of 2.5 V (TYP), which is used as the operating power supply for all the Internal. The CTL pin is used to turn ON/OFF the reference voltage. Furthermore, this reference voltage has a current capacitance of 1 mA (MIN) or more, from which a high-accuracy reference voltage can be generated through dividing resistance.

## ERRAMP block

The ERRAMP block is an error amplifier to amplify potential between the NON and the INV pins and then output a voltage. The FB pin output voltage determines the output pulse Duty. When the FB voltage reaches 1.95 V (TYP) or more, switching will be OFF (Duty=0\%). When the FB voltage reaches 1.45 V (TYP) or less, the output NPN $\operatorname{Tr}$ will be FULL ON (Duty=100\%).

## OSC block

The OSC block is a block to determine the switching frequency through the RT and the CT pins. RT and CT voltages determine the triangular waveform.

## TIMER LATCH block

The TIMER LATCH block is an output short circuit protection circuit to detect output short circuit when the output voltage from the FB pin of the error amplifier reaches 1 V (TYP) or less. When the FB voltage reaches 1 V (TYP) or less, the TIMER will starts operating to charge the SCP pin at a current capacitance of $7 \mu \mathrm{~A}$ (TYP). When the SCP voltage reaches 1.8 V (TYP), the LATCH will be activated to shut down the circuit.

## PWM/Driver block

The PWM/Driver block is a PWM comparator to determine Duty value differences between output from the error amplifier and the oscillator triangular wave. The DTC voltage determines the maximum duty ratio. When the DTC voltage reaches 1.95 V (TYP), the switching OFF is activated. FULL ON will be activated when the DTC voltage reaches 1.45 V (TYP). The DTC voltage setting should be made through dividing resistance with the VREF block.

- Basic operation


Fig. 13 Basic operation

- When the short circuit protection is activated


Fig. 14 Timing when the short circuit protection is activated

- External component setting procedure
(1) Design of feedback resistance constant

Set step-down, step-up, and inverting feedback resistance as shown below. Set resistance in the range of $1 \mathrm{k} \Omega$ to $330 \mathrm{k} \Omega$. Setting the resistance to $1 \mathrm{k} \Omega$ or less will result in degraded power efficiency, while setting it to $330 \mathrm{k} \Omega$ or more will increase the offset voltage due to the input bias current of $0.1 \mu \mathrm{~A}$ (TYP) of the error amplifier.

- Step-down voltage

Vo


Fig. 16 Step-up voltage

- Inverting voltage Vo (Negative)

Fig. 17 Inverting voltage

$$
V_{0}=\frac{R 8+R 9}{R 9} \times 1.25[\mathrm{~V}]
$$

$$
V_{o}=\frac{R 8+R 9}{R 9} \times 1.25[\mathrm{~V}]
$$

(2) Setting of oscillation frequency Connecting a resistor and capacitor to the RT pin (pin 2) and the CT pin (pin 3) will set the triangular wave oscillation frequency. The RT determines the charge/discharge current to the capacitor. Referring to Fig. 18, set RT resistor and the CT capacitor. Recommended setting ranges are 5 to $100 \mathrm{k} \Omega$ for the CT resistor, 33 to 1000 pF for the CT capacitor, and 20 kHz to 800 kHz for the oscillation frequency. Any setting outside of these ranges may turn OFF switching, thus impairing the operation guarantee.


Fig. 18 RT/CT vs. Frequency
(3) Setting of DTC voltage

Applying the VDTC voltage to the DTC pin (pin 1) will fix the maximum duty ratio.This will serve to prevent the power transistor (FET) from being FULL ON. Fig. 19 shows the relationship between the DTC voltage and the maximum duty ratio. Referring to this Figure, set the DTC voltage.Next, generate the VdTc by dividing the Vref voltage with resistance and then input the VDTC in the DTC pin.


Fig. 19 DTC voltage vs. Maximum duty
Furthermore, the maximum duty ratio should be designed so as not to become a maximum duty for the normal use. The following section shows ranges for the normal use.

$$
\begin{aligned}
& \text { - Step-down voltage } \\
& \text { ONDutyMAX }=\frac{\text { VOMAX }}{\text { VCCMIN }}
\end{aligned}
$$

- Step-up voltage

ONDutyMAX $=\frac{\text { VOMAX - VOMIN }}{\text { VOMAX }}$

$$
\begin{aligned}
& \text { • nverting voltage } \\
& \text { ONDutyMAX }=\frac{\text { VOMAX }}{\text { VOMAX - VCCMIN }}
\end{aligned}
$$

(4) Setting of soft start time

Adding a capacitor to the DTC resistance divider will enable the soft start function activation.
The soft start function will be required to prevent an excessive increase in the coil current and overshoot of the output voltage, while in startup operation. Fig. 20 shows the relationship between the capacitor and the soft start time. Referring to this Figure, set the capacitor. It is recommended to set the capacitance value in the range of 0.01 to $10 \mu \mathrm{~F}$. Setting the capacitance value to $0.01 \mu \mathrm{~F}$ or less, may cause overshoot to the output voltage, while setting it to $10 \mu \mathrm{~F}$ or more may cause an inverse current in the internal parasitic diode when the power supply is grounded, thus resulting in damage to the internal element.
the internal element.


Fig. 20 Soft start capacitance vs. Delay time


Fig. 21 ON/OFF peak circuit

Since the PNP Tr is generally slow in switching, in terms of the sat characteristics, the ON/OFF peak circuit is used as an acceleration circuit. The D1 and the C7 generate an ON peak current, while the Q1 and the C7 forms an OFF peak circuit.Set pull-up resistance to $510 \Omega$ as a guide at $\mathrm{VCC}=12 \mathrm{~V}$. It is recommended to set this resistance in the range of $100 \mathrm{k} \Omega$ to $10 \mathrm{k} \Omega$. In order to make adjustment of the R 6 and R 7 , however, pay attention of the points listed in table below.

| NO. | Item | To reduce R6 | To reduce R7 |
| :---: | :---: | :---: | :---: |
| 1 | Efficiency | Degraded | Degraded |
| 2 | Tr Turn ON / Turn OFF | Faster Turn OFF | Faster Turn OFF |
| 3 | Switching frequency | Increasable | Increasable |
| 4 | Load current capacitance | Degraded | Degraded |

Take 1000 pF as a guide for the C 7 setting. If the ON/OFF peak currents are inadequate, increase the C 7 capacitance value. It is recommended to set capacitance values in the range of 100 pF to 10000 pF . Setting the capacitance value to 10000 pF or more may increase the peak current and degrade the power efficiency.
(6) Phase compensation

Phase compensation setting procedure
The phase compensation setting procedure varies with the selection of output capacitors used for DC/DC converter application. In this connection, the following section describes the procedure by classifying into the two types. Furthermore, the application stability conditions are described in the Description section.

1. Application stability conditions
2. For output capacitors having high ESR, such as electrolytic capacitor
3. For output capacitors having low ESR, such as ceramic capacitor or OS-CON
4. Application stability conditions

The following section shows the stability conditions of negative feedback system.

- DSC, DVD, printer, DVD/DVD recorder, and other consumer productsAt a 1 (0-dB) gain, the phase delay is $150^{\circ}$ or less (i.e., the phase margin is $30^{\circ}$ or more).

Furthermore, since the DC/DC converter application is sampled according to the switching frequency, GBW of the overall system should be set to $1 / 10$ or less of the switching frequency. The following section summarizes the targeted characteristics of this application.

- DSC, DVD, printer, DVD/DVD recorder, and other consumer productsAt a $1(0-\mathrm{dB})$ gain, the phase delay is $150^{\circ}$ or less (i.e., the phase margin is $30^{\circ}$ or more).
- DSC, DVD, printer, DVD/DVD recorder, and other consumer productsThe GBW (i.e., frequency at 0-dB gain) for this occasion is $1 / 10$ or less of the switching frequency.

In other words, the responsiveness is determined with restrictions on the GBW. Consequently, in order to upgrade the responsiveness, higher switching frequency should be provided.

In order to ensure the stability through the phase compensation, a secondary phase delay ( $-180^{\circ}$ ) resulting from LC resonance should be canceled with a secondary phase lead (i.e., through inserting two phase leads). Furthermore, the GBW (i.e., frequency at 1-dB gain) is determined according to phase compensation capacitance to be provided for the error amplifier. Consequently, in order to reduce the GBW, increase the capacitance value.
(1) Typical (sun) integrator (Low pass filter)
(2) Open loop characteristics of (mon) integrator


(a) point $\quad f a=\frac{1}{2 \pi R C A}[H z]$
(b) point $\mathrm{fb}=\mathrm{GBW}=\frac{1}{2 \pi \mathrm{RC}}[\mathrm{Hz}]$

Fig. 22 Typical integrator characteristics

Since the error amplifier is provided with (sun) or (mon) phase compensation, the low pass filter is applied. In the case of the DC/DC converter application, the R becomes a parallel resistance of the feedback resistance.
2. For output capacitors having high ESR, such as aluminum electrolytic capacitor

For output capacitors having high ESR (i.e., several ohms), the phase compensation setting procedure becomes comparatively simple. Since the DC/DC converter application has a LC resonant circuit attached to the output, a $-180^{\circ}$ phase-delay occurs in that area. If ESR component is present there, however, a $+90^{\circ}$ phase-lead occurs to shift the phase delay to $-90^{\circ}$. Since the phase delay is desired to set within $150^{\circ}$, this is a very effective method but has a demerit to increase the ripple component of the output voltage.
(3) LC resonant circuit


At this resonance point, a $-180^{\circ}$ phase-delay occurs.
(4) With ESR provided

$\mathrm{f}_{\mathrm{z}}=\frac{1}{2 \pi \sqrt{\mathrm{LC}_{1}}}[\mathrm{~Hz}]:$ Resonance point $\mathrm{fESR}=\frac{1}{2 \pi \text { ResrC }}[\mathrm{Hz}]$ : Phase lead A $-90^{\circ}$ phase-delay occurs.

* Same for the phase compensation of inverting and step-up voltages

Fig. 23 DC/DC converter output application

According to changes in phase characteristics due to the ESR, only one phase lead should be inserted. For this phase lead, select either of the methods shown below:
(5) Insert feedback resistance in the C.


Phase lead: $\mathrm{fz}=\frac{1}{2 \pi \mathrm{C} 1 \mathrm{R} 1}[\mathrm{~Hz}]$
(6) Insert the R3 in integrator.


Phase lead: $\mathrm{fz}=\frac{1}{2 \pi \mathrm{C} 2 \mathrm{R} 3}[\mathrm{~Hz}]$

Fig. 24 Typical phase compensation circuit

To cancel the LC resonance, phase lead frequency should be set close to the LC resonant frequency.
3. For output capacitors having low ESR, such as a ceramic capacitor or OS-CON

In order to use capacitors having low ESR (i.e., several tens of mW ), two phase-leads should be inserted so that a $-180^{\circ}$ phase-dela y, due to LC resonance, will be compensated. The following section shows a typical phase compensation procedure.

- Phase compensation with secondary phase lead


$$
\begin{aligned}
& \text { Phase lead: } \mathrm{fz} 1=\frac{1}{2 \pi \mathrm{R} 1 \mathrm{C} 1}[\mathrm{~Hz}] \\
& \text { Phase lead: } \mathrm{fz} 2=\frac{1}{2 \pi \mathrm{R} 3 \mathrm{C} 2}[\mathrm{~Hz}] \\
& \text { LC resonant frequency: } \mathrm{fr}=\frac{1}{2 \pi \sqrt{\mathrm{LC}}}[\mathrm{~Hz}]
\end{aligned}
$$

Fig. 25 Typical circuit after secondary compensation circuit
For the settings of phase lead frequency, insert both of the phase leads close to the LC resonant frequency.

Phase compensation on the BD9300F/FV
For BD9300F/FV, since the error amplifier input is inverted to the normal input, the phase compensation procedure is slightly different. (The BD9300F/FV returns feedback to the NON pin.)


Fig. 26 Typical circuit after phase compensation on BD9300F/FV

The BD9300F/FV feeds back on the + side input and returns the phase compensation on the - side input. Consequently, resistance of the resistance divider being used to determine the reference voltage has influence on the frequency characteristics. (The BD9300F/FV has a $1 / 2$ VREF pin to divide resistance by $100 \mathrm{k} \Omega$.)

The following section shows the phase characteristics.

$$
\begin{aligned}
& \text { Primary phase delay: } \mathrm{fp}=\frac{1}{2 \pi \mathrm{C} \frac{100 \mathrm{k} \Omega}{2}(1+\mathrm{A})}[\mathrm{Hz}] \text {, where } \mathrm{A} \text { is approximately } 80 \mathrm{~dB} . \\
& \text { Phase lead: } \quad \mathrm{fz}=\frac{1}{2 \pi \mathrm{C} \frac{100 \mathrm{k} \Omega}{2}}[\mathrm{~Hz}]
\end{aligned}
$$

As a result, inserting a phase compensation capacitor will cause phase lead component. If any further phase lead is required, add a capacitor in parallel with the R1.
(1) DTC


1) Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.
2) GND potential

Ground-GND potential should maintain at the minimum ground voltage level. Furthermore, no terminals should be lower than the GND potential voltage including an electric transients.
3) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation $(\mathrm{Pd})$ in actual operating conditions.
4) Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if positive and ground power supply terminals are reversed. The IC may also be damaged if pins are shorted together or are shorted to other circuitís power lines.
5) Operation in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.
6) Testing on application boards

When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Always turn the IC's power supply off before connecting it to, or removing it from a jig or fixture, during the inspection process. Ground the IC during assembly steps as an antistatic measure. Use similar precaution when transporting and storing the IC.
7) IC pin input

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements to keep them isolated. PñN junctions are formed at the intersection of these $P$ layers with the $N$ layers of other elements, creating a parasitic diode or transistor. For example, the relation between each potential is as follows:When GND > Pin A and GND > Pin B, the PñN junction operates as a parasitic diode.
When Pin B > GND > Pin A, the PñN junction operates as a parasitic transistor.
Parasitic diodes can occur inevitably in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND (P substrate) voltage to an input pin, should not be used.

8) Ground wiring pattern

The power supply and ground lines must be as short and thick as possible to reduce line impedance. Fluctuating voltage on the power ground line may damage the device.

- Derating curve


Fig. 29 Thermal derating characteristics

- Selection of order type



## - Package specifications

## SOP14



| <Package specifications> |  |
| :---: | :---: |
| Package style | Embossed carrier tape |
| Q'ty per package | 2500pcs |
| Packaging direction | E2 <br> (When holding a reel by left hand and pulling out the tape by right hand, No. 1 pin appears in the upper left of the reel.) |
|  |  |

## SSOP-B14

| <Outline dimensions> |  |
| :---: | :---: |
|  | (Unit:mm) |



The contents described herein are correct as of September, 2008
The contents described herein are subject to change without notice. For updates of the latest information, please contact and confirm with ROHM CO.,LTD.
Any part of this application note must not be duplicated or copied without our permission.
Application circuit diagrams and circuit constants contained herein are shown as examples of standard use and operation. Please pay careful attention to the peripheral conditions when designing circuits and deciding
upon circuit constants in the set.
Any data, including, but not limited to application circuit diagrams and information, described herein are intended only as illustrations of such devices and not as the specifications for such devices. ROHM CO.,LTD. disclaims any warranty that any use of such devices shall be free from infringement of any third party's intellectual property rights or other proprietary rights, and further, assumes no liability of whatsoever nature in the event of any such infringement, or arising from or connected with or related to the use of such devices.

- Upon the sale of any such devices, other than for buyer's right to use such devices itself, resell or otherwise dispose of the same, implied right or license to practice or commercially exploit any intellectual property rights or other proprietary rights owned or controlled by ROHM CO., LTD. is granted to any such buyer.
The products described herein utilize silicon as the main materia
- The products described herein are not designed to be $X$ ray proof.

The products listed in this catalog are designed to be used with ordinary electronic equipment or devices (such as audio visual equipment, office-automation equipment, communications devices, electrical appliances and electronic toys).
Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.


## Notice

## Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ${ }^{(N o t e ~ 1)}$, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.
(Note1) Medical Equipment Classification of the Specific Applications

| JAPAN | USA | EU | CHINA |
| :---: | :---: | :---: | :---: |
| CLASSII | CLASSIII | CLASS II b | CLASSIII |
|  |  | CLASSIII |  |

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
[a] Installation of protection circuits or other protective devices to improve system safety
[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
[a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
[b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
[c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including $\mathrm{Cl}_{2}$, $\mathrm{H}_{2} \mathrm{~S}, \mathrm{NH}_{3}, \mathrm{SO} 2$, and $\mathrm{NO}_{2}$
[d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
[e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
[f] Sealing or coating our Products with resin or other coating materials
[g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
[h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

## Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

## Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

## Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
[a] the Products are exposed to sea winds or corrosive gases, including Cl2, $\mathrm{H} 2 \mathrm{~S}, \mathrm{NH} 3, \mathrm{SO} 2$, and NO 2
[b] the temperature or humidity exceeds those recommended by ROHM
[c] the Products are exposed to direct sunshine or condensation
[d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

## Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

## Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

## Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

## Precaution Regarding Intellectual Property Rights

1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data.
2. ROHM shall not have any obligations where the claims, actions or demands arising from the combination of the Products with other articles such as components, circuits, systems or external equipment (including software).
3. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the Products or the information contained in this document. Provided, however, that ROHM will not assert its intellectual property rights or other rights against you or your customers to the extent necessary to manufacture or sell products containing the Products, subject to the terms and conditions herein.

## Other Precaution

1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
3. In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

## General Precaution

1. Before you use our Products, you are requested to care fully read this document and fully understand its contents. ROHM shall not be in an y way responsible or liable for failure, malfunction or accident arising from the use of a ny ROHM's Products against warning, caution or note contained in this document.
2. All information contained in this docume nt is current as of the issuing date and subj ect to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the la test information with a ROHM sale s representative.
3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate an d/or error-free. ROHM shall not be in an y way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components
Click to view similar products for Switching Controllers category:
Click to view products by ROHM manufacturer:

Other Similar products are found below :
AZ7500EP-E1 NCP1218AD65R2G NCP1234AD100R2G NCP1244BD065R2G NCP1336ADR2G NCP6153MNTWG NCP81101BMNTXG
NCP81205MNTXG SJE6600 SMBV1061LT1G SG3845DM NCP4204MNTXG NCP6132AMNR2G NCP81102MNTXG
NCP81203MNTXG NCP81206MNTXG NX2155HCUPTR UBA2051C FSL4110LRLX MAX8778ETJ+ NTBV30N20T4G
NCP1240AD065R2G NCP1240FD065R2G NCP1361BABAYSNT1G NTC6600NF NCP1230P100G NCP1612BDR2G NX2124CSTR SG2845M NCP81101MNTXG TEA19362T/1J IFX81481ELV NCP81174NMNTXG NCP4308DMTTWG NCP4308DMNTWG NCP4308AMTTWG NCP1251FSN65T1G NCP1246BLD065R2G NTE7154 NTE7242 LTC7852IUFD-1\#PBF LTC7852EUFD-1\#PBF MB39A136PFT-G-BND-ERE1 NCP1256BSN100T1G LV5768V-A-TLM-E NCP1365BABCYDR2G NCP1365AABCYDR2G MCP1633TE/MG NCV1397ADR2G NCP1246ALD065R2G

